

P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY			
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A)	Q _g (TYP.) (nC)
-20	0.450 at V _{GS} = -4.5 V	-0.55	1
	0.500 at V _{GS} = -2.5 V	-0.50	
	0.600 at V _{GS} = -1.8 V	-0.38	

FEATURES

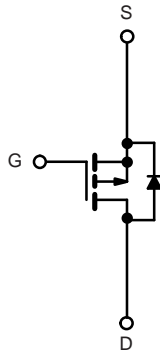
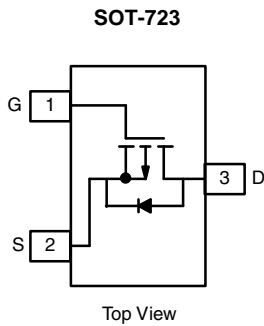
- TrenchFET® power MOSFET
- 100 % R tested
- Fast switching speed



RoHS
COMPLIANT
HALOGEN
FREE

APPLICATIONS

- Load / power switch for portable devices
- Drivers: relays, solenoids, displays
- Battery operated systems



P-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS (T _A = 25 °C, unless otherwise noted)			
PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	-20	V
Gate-Source Voltage	V _{GS}	± 8	
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	-0.55 ^{b, c}	A
	T _A = 70 °C	-0.45 ^{b, c}	
Pulsed Drain Current (t = 300 μs)	I _{DM}	-1.8	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	-0.16 ^{b, c}
Maximum Power Dissipation	T _A = 25 °C	P _D	0.19 ^{b, c}
	T _A = 70 °C		0.12 ^{b, c}
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to +150	°C

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum Junction-to-Ambient ^{a, b}	t ≤ 5 s	440	530	°C/W	
	Steady State	540	650		

Notes

- Maximum under steady state conditions is 650 °C/W.
- Surface mounted on 1" x 1" FR4 board.
- t = 5 s.

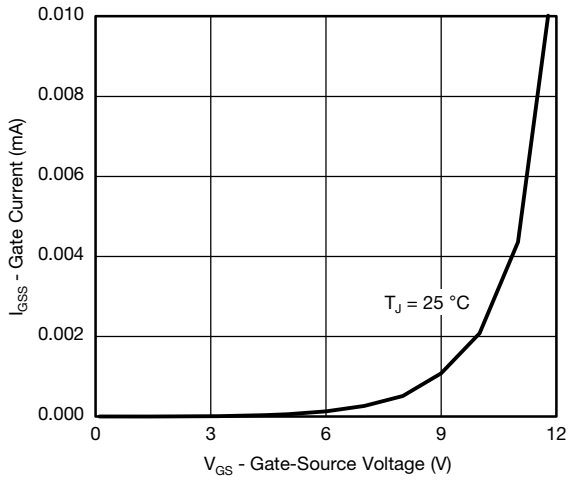
SPECIFICATIONS ($T_J = 25\text{ }^\circ\text{C}$, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-Source Breakdown Voltage	V_{DS}	$V_{GS} = 0, I_D = -250\ \mu\text{A}$	-20	-	-	V	
V_{DS} Temperature Coefficient	$\Delta V_{DS}/T_J$	$I_D = -250\ \mu\text{A}$	-	-12	-	mV/ $^\circ\text{C}$	
$V_{GS(th)}$ Temperature Coefficient	$\Delta V_{GS(th)}/T_J$		-	1.8	-		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = -250\ \mu\text{A}$	-0.4	-	-1	V	
Gate-Source Leakage	I_{GSS}	$V_{DS} = 0\ \text{V}, V_{GS} = \pm 8\ \text{V}$	-	-	± 30	μA	
		$V_{DS} = 0\ \text{V}, V_{GS} = \pm 4.5\ \text{V}$	-	-	± 1		
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20\ \text{V}, V_{GS} = 0\ \text{V}$	-	-	-1		
		$V_{DS} = -20\ \text{V}, V_{GS} = 0\ \text{V}, T_J = 85\text{ }^\circ\text{C}$	-	-	-10		
On-State Drain Current ^a	$I_{D(on)}$	$V_{DS} \geq 5\ \text{V}, V_{GS} = -4.5\ \text{V}$	-1.5	-	-	A	
Drain-Source On-State Resistance ^a	$R_{DS(on)}$	$V_{GS} = -4.5\ \text{V}, I_D = -0.4\ \text{A}$	-	0.450	-	Ω	
		$V_{GS} = -2.5\ \text{V}, I_D = -0.2\ \text{A}$	-	0.500	-		
		$V_{GS} = -1.8\ \text{V}, I_D = -0.1\ \text{A}$	-	0.600	-		
Forward Transconductance	g_{fs}	$V_{DS} = -10\ \text{V}, I_D = 0.4\ \text{A}$	-	1	-	S	
Dynamic ^b							
Input Capacitance	C_{iss}	$V_{DS} = -10\ \text{V}, V_{GS} = 0\ \text{V}, f = 1\ \text{MHz}$	-	45	-	μF	
Output Capacitance	C_{oss}		-	15	-		
Reverse Transfer Capacitance	C_{rss}		-	10	-		
Total Gate Charge	Q_g	$V_{DS} = -10\ \text{V}, V_{GS} = -4.5\ \text{V}, I_D = -0.4\ \text{A}$	-	1.65	2.50	nC	
			-	1	2		
Gate-Source Charge	Q_{gs}	$V_{DS} = -0\ \text{V}, V_{GS} = -2.5\ \text{V}, I_D = -0.4$	-	0.2	-		
Gate-Drain Charge	Q_{gd}		-	0.26	-		
Gate Resistance	R_g		$f = 1\ \text{MHz}$	2.4	12		24
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\ \text{V}, R_L = 33.3\ \Omega$ $I_D \cong -0.3\ \text{A}, V_{GEN} = -4.5\ \text{V}, R_g = 1\ \Omega$	-	9	18		ns
Rise Time	t_r		-	10	20		
Turn-Off Delay Time	$t_{d(off)}$		-	10	20		
Fall Time	t_f		-	8	16		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\ \text{V}, R_L = 33.3\ \Omega$ $I_D \cong -0.3\ \text{A}, V_{GEN} = -8\ \text{V}, R_g = 1\ \Omega$	-	1	2		
Rise Time	t_r		-	8	16		
Turn-Off Delay Time	$t_{d(off)}$		-	9	18		
Fall Time	t_f		-	5	10		
Drain-Source Body Diode Characteristics							
Pulse Diode Forward Current ^a	I_{SM}		-	-	-1.5	A	
Body Diode Voltage	V_{SD}	$I_S = -0.3\ \text{A}$	-	-0.8	-1.2	V	
Body Diode Reverse Recovery Time	t_{rr}	$I_F = -0.3\ \text{A}, di/dt = 100\ \text{A}/\mu\text{s}$	-	16	24	ns	
Body Diode Reverse Recovery Charge	Q_{rr}		-	8	16	nC	
Reverse Recovery Fall Time	t_a		-	11	-	ns	
Reverse Recovery Rise Time	t_b		-	5	-		

Notes

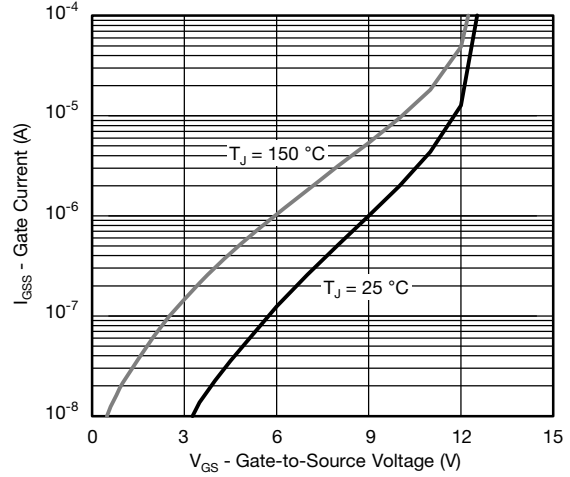
- a. Pulse test; pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\%$.
 b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

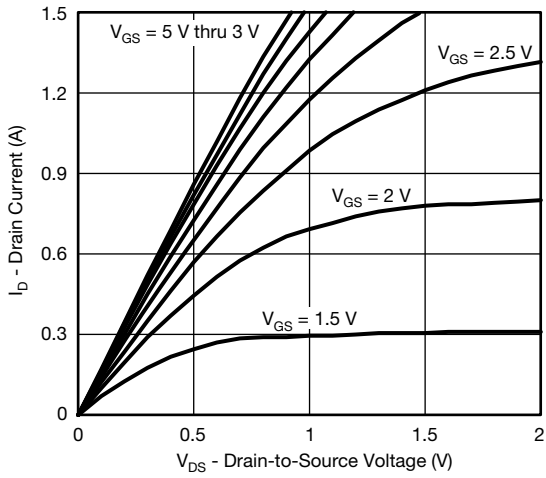
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



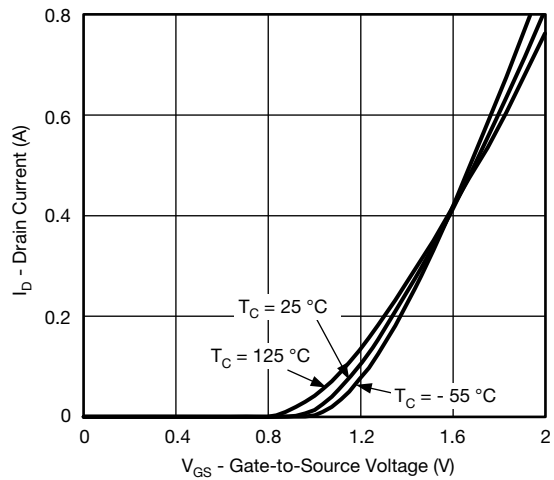
Gate Current vs. Gate-Source Voltage



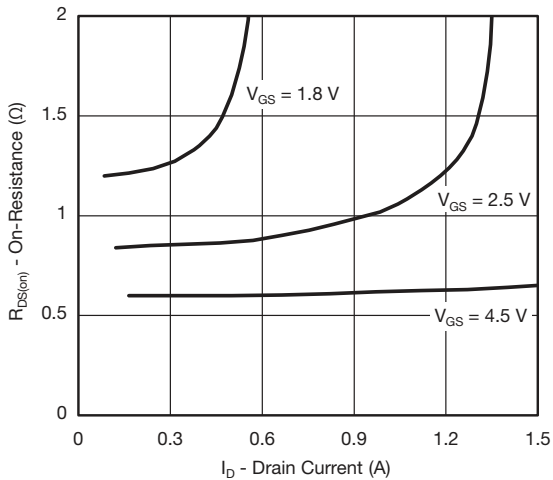
Gate Current vs. Gate-Source Voltage



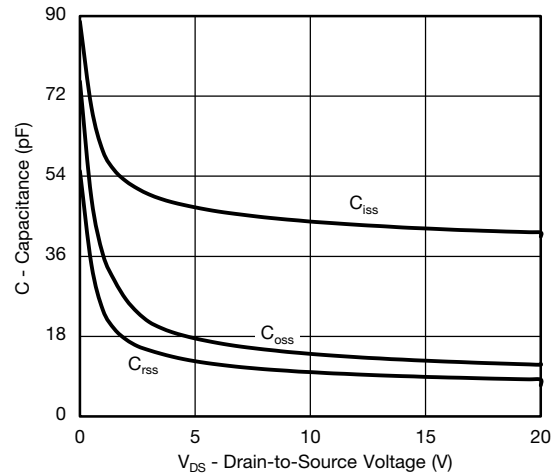
Output Characteristics



Transfer Characteristics

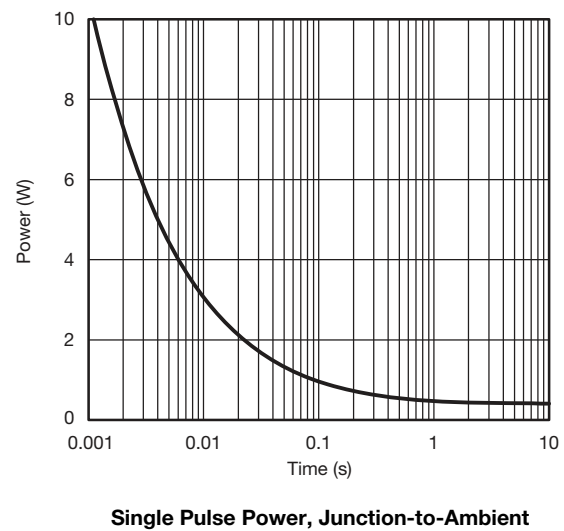
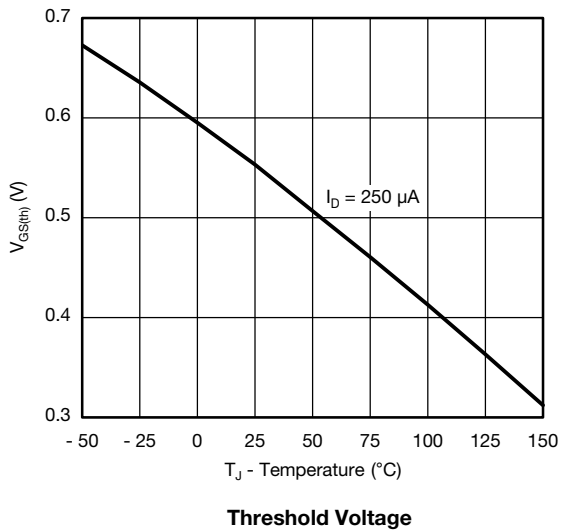
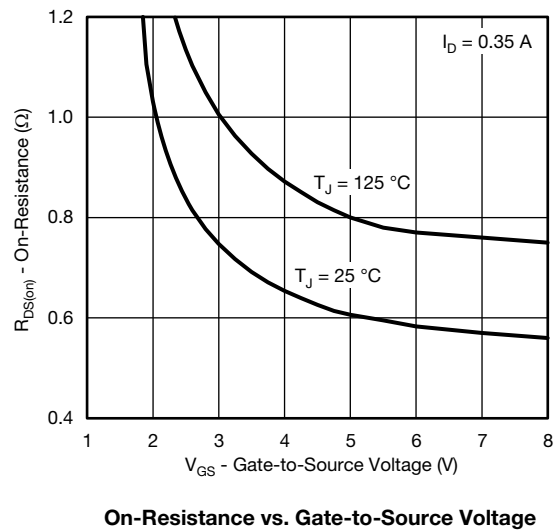
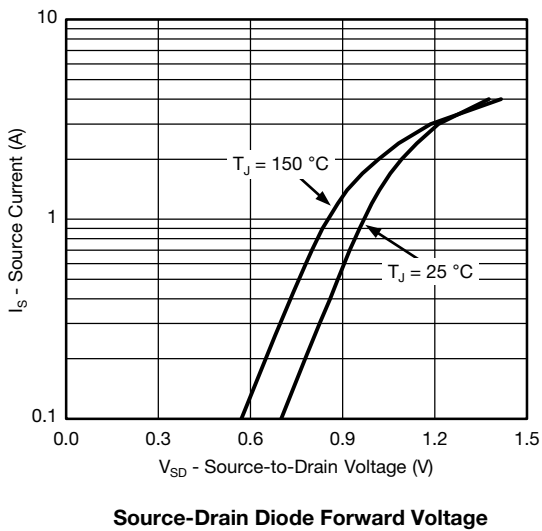
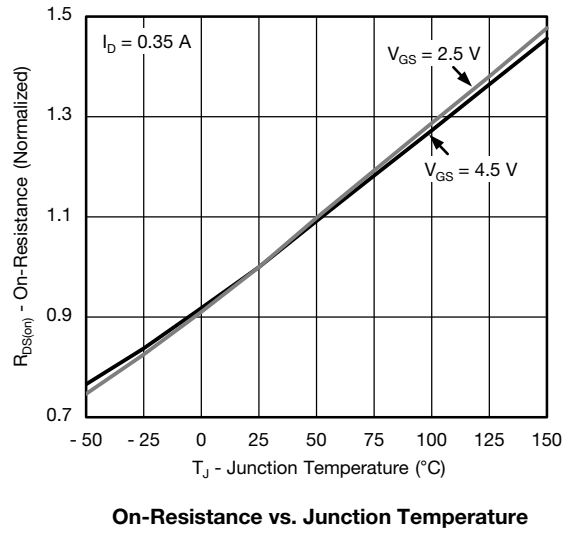
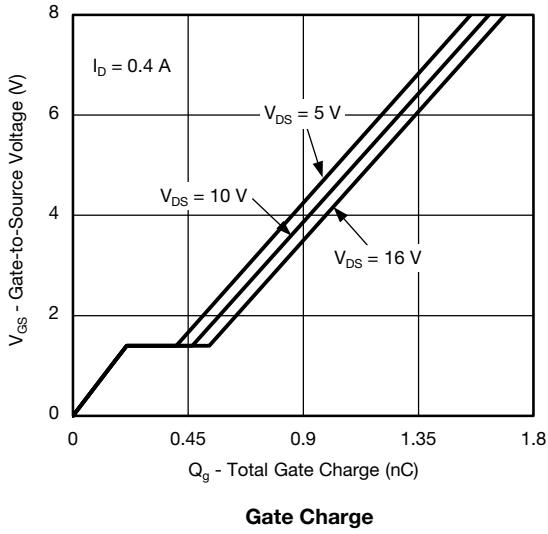


On-Resistance vs. Drain Current

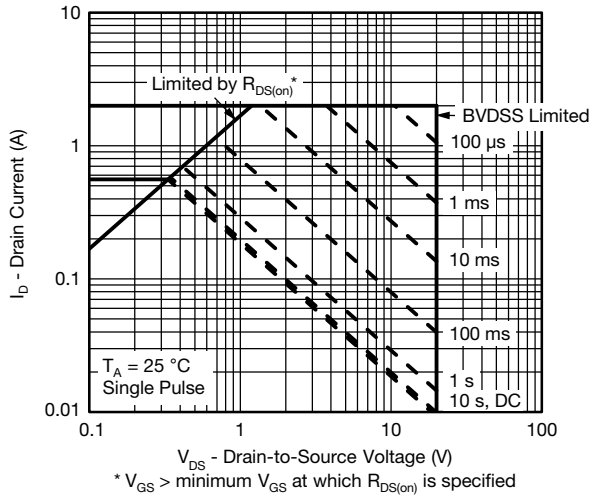


Capacitance

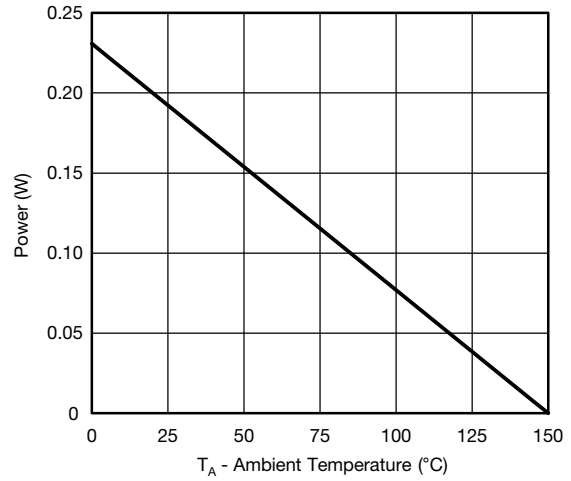
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



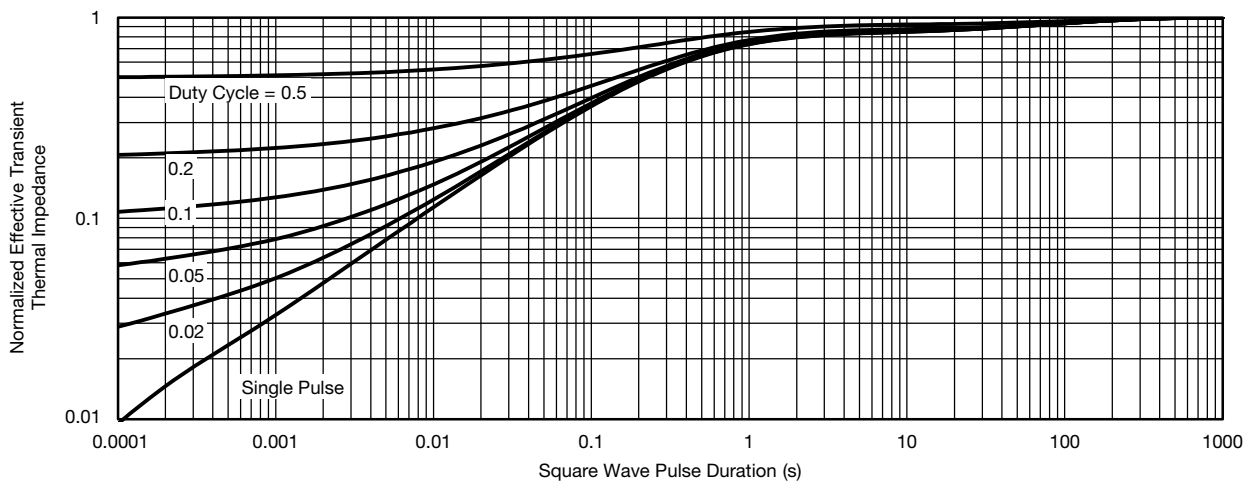
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Safe Operating Area, Junction-to-Ambient

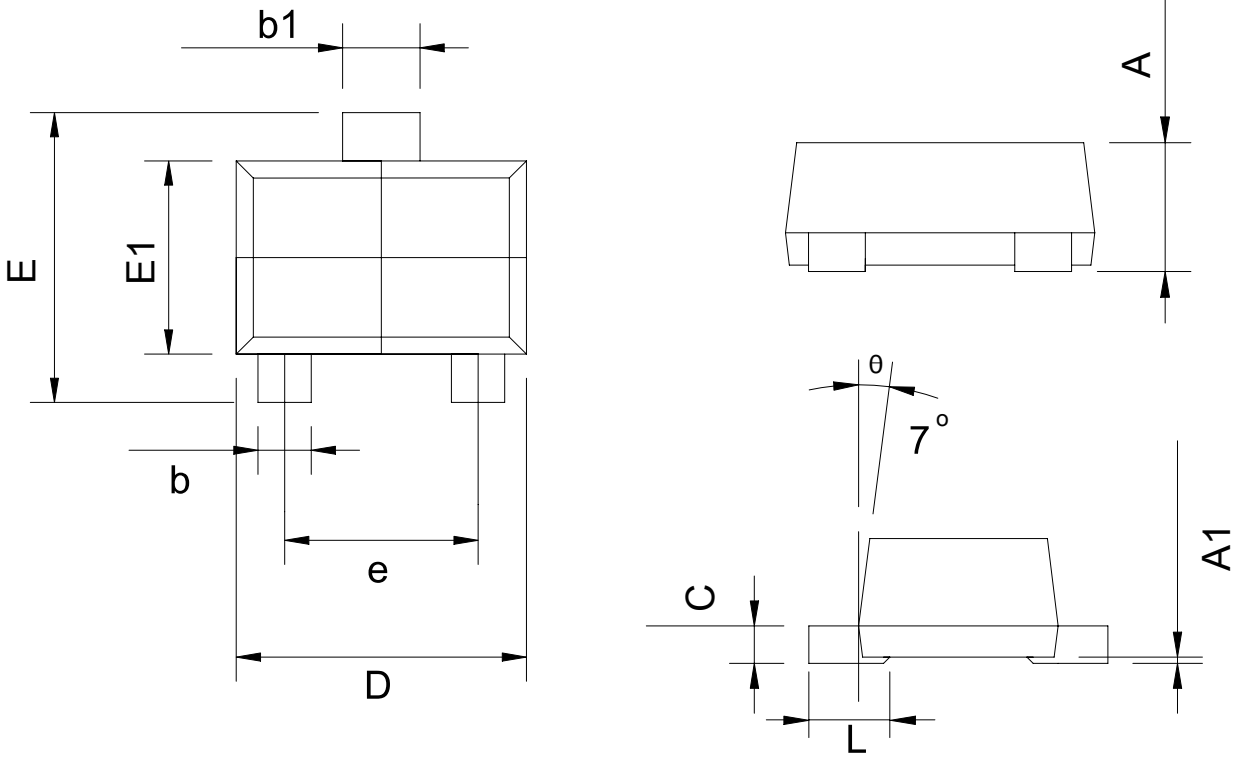


Power Derating, Junction-to-Ambient



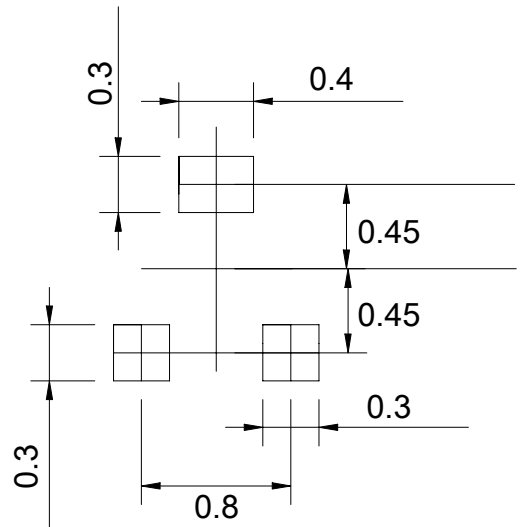
Normalized Thermal Transient Impedance, Junction-to-Ambient

SOT-723: 3 Leads



SYMBOLS	SOT-723			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	-	0.500	-	0.020
A1	0.000	0.050	0.000	0.002
b	0.170	0.270	0.007	0.011
b1	0.270	0.370	0.011	0.015
c	-	0.150	-	0.006
D	1.150	1.250	0.045	0.049
E	1.150	1.250	0.045	0.049
E1	0.750	0.850	0.030	0.033
e	0.800 TYP.		0.031 TYP.	
L	0.32 BSC		0.013 BSC	
-	° REF.		° REF.	

RECOMMENDED LAND PATTERN



UNIT: mm

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